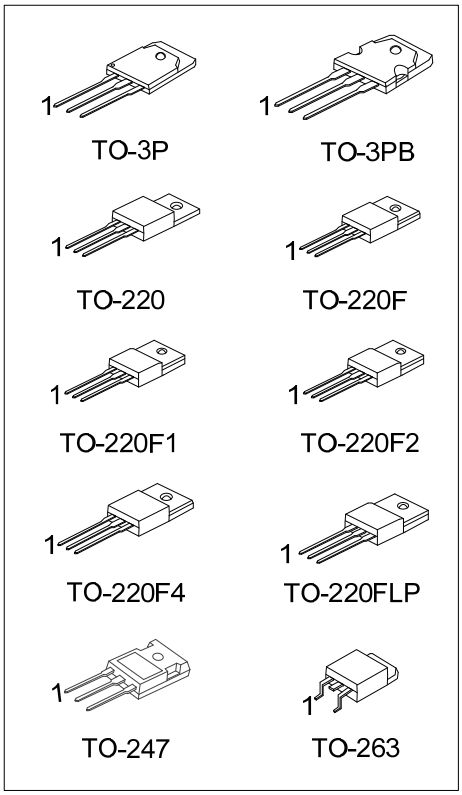
13NM90

Power MOSFET

13A, 900V N-CHANNEL SUPER-JUNCTION MOSFET



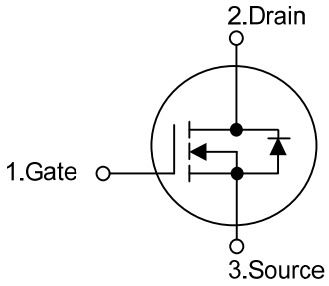
■ DESCRIPTION

The **UTC 13NM90** is a Super Junction MOSFET Structure and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and a high rugged avalanche characteristics. This power MOSFET is usually used at AC-DC converters for power applications.

■ FEATURES

* $R_{DS(ON)} \leq 0.5\ \Omega$ @ V_{GS}=10V, I_D=6.5A
* Fast switching capability
* Avalanche energy tested
* Improved dv/dt capability, high ruggedness

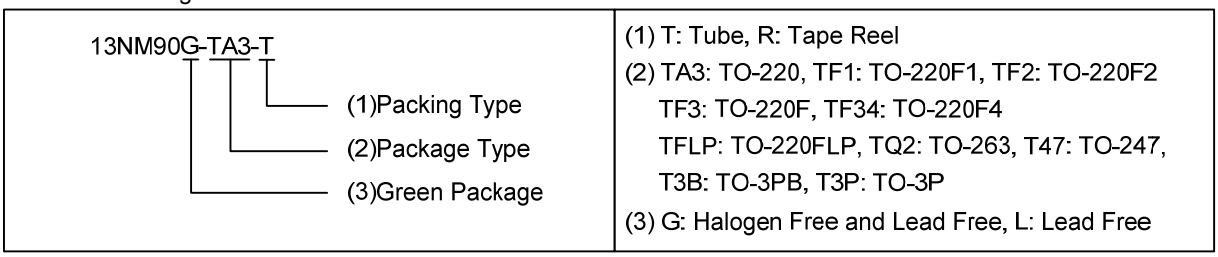
■ SYMBOL



■ ORDERING INFORMATION

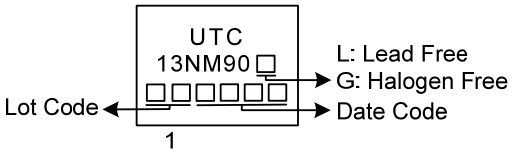
Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen Free		1	2	3	
13NM90L-TA3-T	13NM90G-TA3-T	TO-220	G	D	S	Tube
13NM90L-TF1-T	13NM90G-TF1-T	TO-220F1	G	D	S	Tube
13NM90L-TF2-T	13NM90G-TF2-T	TO-220F2	G	D	S	Tube
13NM90L-TF3-T	13NM90G-TF3-T	TO-220F	G	D	S	Tube
13NM90L-TF34-T	13NM90G-TF34-T	TO-220F4	G	D	S	Tube
13NM90G-TFLP-T	13NM90G-TFLP-T	TO-220FLP	G	D	S	Tube
13NM90L-TQ2-T	13NM90G-TQ2-T	TO-263	G	D	S	Tube
13NM90L-TQ2-R	13NM90G-TQ2-R	TO-263	G	D	S	Tape Reel
13NM90L-T3B-T	13NM90G-T3B-T	TO-3PB	G	D	S	Tube
13NM90L-T3P-T	13NM90G-T3P-T	TO-3P	G	D	S	Tube
13NM90L-T47-T	13NM90G-T47-T	TO-247	G	D	S	Tube

Note: Pin Assignment: G: Gate D: Drain S: Source



(1) T: Tube, R: Tape Reel
(2) TA3: TO-220, TF1: TO-220F1, TF2: TO-220F2
TF3: TO-220F, TF34: TO-220F4
TFLP: TO-220FLP, TQ2: TO-263, T47: TO-247,
T3B: TO-3PB, T3P: TO-3P
(3) G: Halogen Free and Lead Free, L: Lead Free

■ MARKING



■ ABSOLUTE MAXIMUM RATINGS (T_C = 25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V_{DSS}	900	V
Gate-Source Voltage		V_{GSS}	±30	V
Continuous Drain Current	Continuous	I_D	13	A
Pulsed Drain Current	Pulsed (Note 2)	I_{DM}	52	A
Avalanche Current (Note 2)		I_{AR}	3.0	A
Single Pulsed Avalanche Energy	Single Pulsed (Note 3)	E_{AS}	180	mJ
Peak Diode Recovery dv/dt (Note 4)		dv/dt	2.68	V/ns
Power Dissipation	TO-220/TO-263	P_D	101	W
	TO-220F1/TO-220F2 TO-220F4/TO-220FLP		32	W
	TO-3P/TO-3PB		405	W
	TO-247		370	W
Junction Temperature		T_J	+150	°C
Storage Temperature		T_{STG}	-55 ~ +150	°C

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
2. Repetitive Rating: Pulse width limited by maximum junction temperature.
3. L = 10mH, I_{AS} = 4.2A, V_{DD} = 50V, R_G = 25Ω, Starting T_J = 25°C.
4. I_{SD} ≤ 13A, di/dt ≤ 200A/μs, V_{DD} ≤ BV_{DSS}, Starting T_J = 25°C.

■ THERMAL DATA

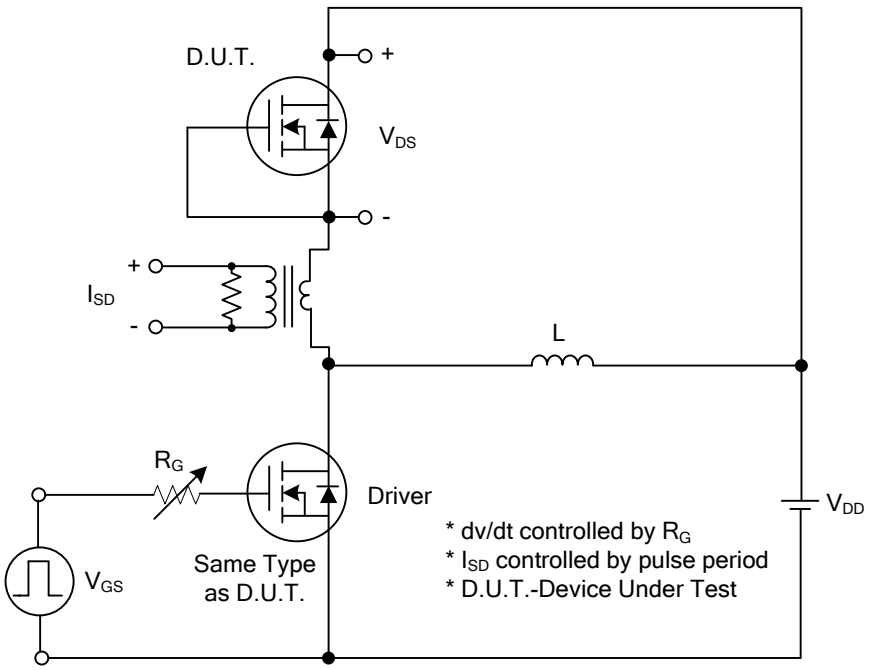
PARAMETER		SYMBOL	RATINGS	UNIT
Junction to Ambient	TO-220/TO-220F1 TO-220F2/TO-220F4 TO-220FLP/TO-263	$θ_{JA}$	62.5	°C/W
	TO-3P/TO-3PB		30	°C/W
	TO-247		40	°C/W
Junction to Case	TO-220/TO-220F1 TO-263	$θ_{JC}$	1.24	°C/W
	TO-220F1/TO-220F2 TO-220F4/TO-220FLP		3.91	°C/W
	TO-3P/TO-3PB		0.31	°C/W
	TO-247		0.34	°C/W

■ ELECTRICAL CHARACTERISTICS (T_J=25°C, unless otherwise specified)

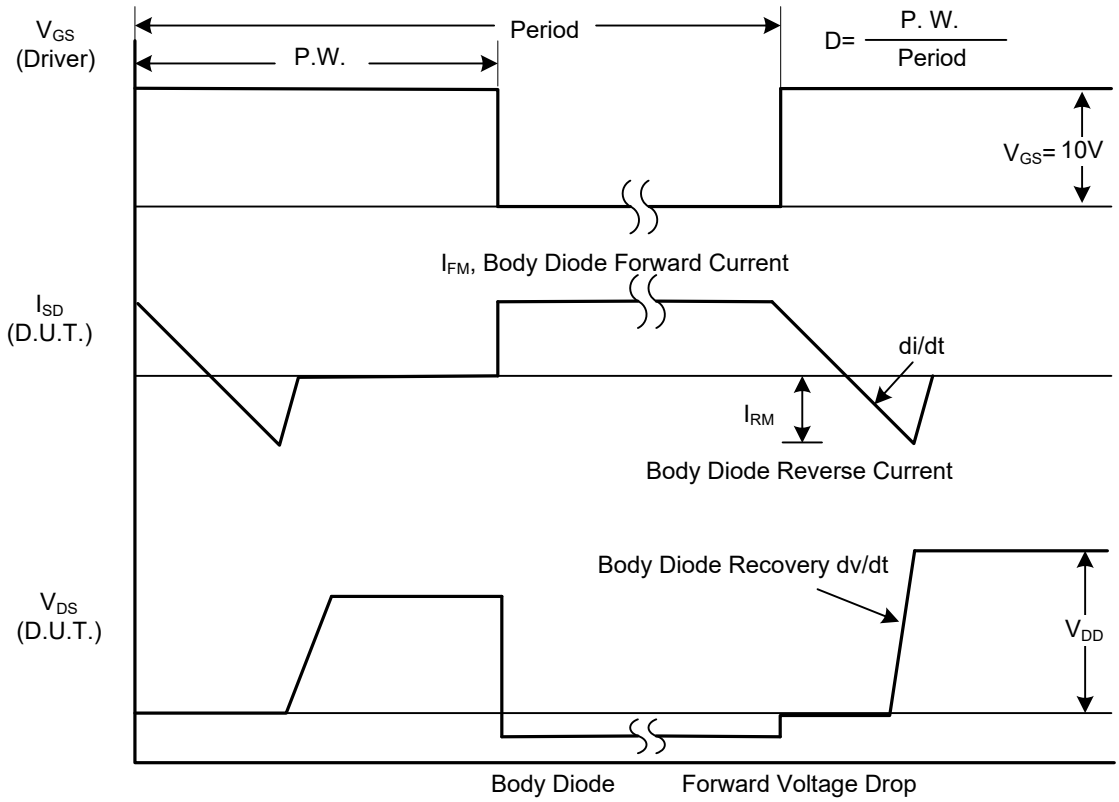
PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage		BV_{DSS}	V_{GS}=0V, I_D=250μA	900			V
Drain-Source Leakage Current		I_{DSS}	V_{DS}=900V, V_{GS}=0V			10	μA
Gate-Source Leakage Current	Forward	I_{GSS}	V_{GS}=30V, V_{DS}=0V			100	nA
	Reverse		V_{GS}=-30V, V_{DS}=0V			-100	nA
ON CHARACTERISTICS							
Gate Threshold Voltage		$V_{GS(TH)}$	V_{DS}=V_{GS}, I_D=250μA	2.5		4.5	V
Static Drain-Source On-State Resistance		$R_{DS(ON)}$	V_{GS}=10V, I_D=6.5A			0.5	Ω
DYNAMIC CHARACTERISTICS							
Input Capacitance		C_{ISS}	V_{GS}=0V, V_{DS}=25V, f=1.0MHz		1650		pF
Output Capacitance		C_{OSS}			390		pF
Reverse Transfer Capacitance		C_{RSS}			0.3		pF
SWITCHING CHARACTERISTICS							
Total Gate Charge (Note 1)		Q_G	V_{DS}=100V, V_{GS}=10V, I_D=13A, I_G=1mA (Note 1,2)		60		nC
Gate to Source Charge		Q_{GS}			11		nC
Gate to Drain Charge		Q_{GD}			22		nC
Turn-ON Delay Time (Note 1)		$t_{D(ON)}$	V_{DS}=100V, V_{GS}=10V, I_D=13A, R_G=25Ω(Note 1,2)		25		nS
Rise Time		t_R			24		nS
Turn-OFF Delay Time		$t_{D(OFF)}$			190		nS
Fall-Time		t_F			37		nS
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS							
Maximum Body-Diode Continuous Current		I_S				13	A
Maximum Body-Diode Pulsed Current		I_{SM}				52	A
Drain-Source Diode Forward Voltage (Note 1)		V_{SD}	I_S=13A, V_{GS}=0V			1.4	V
Body Diode Reverse Recovery Time (Note 1)		t_{rr}	I_S=13A, V_{GS}=0V, dI_F/dt=100A/μs		640		nS
Body Diode Reverse Recovery Charge		Q_{rr}			12.7		μC

Notes: 1. Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2%.
2. Essentially independent of operating ambient temperature.

■ TEST CIRCUITS AND WAVEFORMS

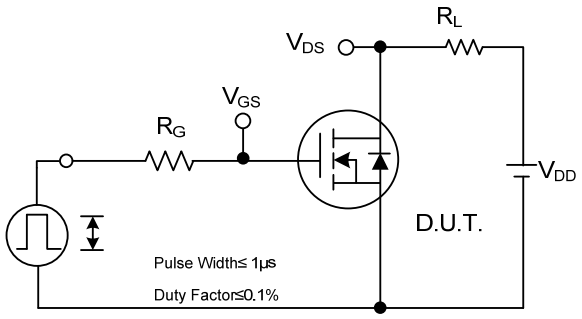


Peak Diode Recovery dv/dt Test Circuit

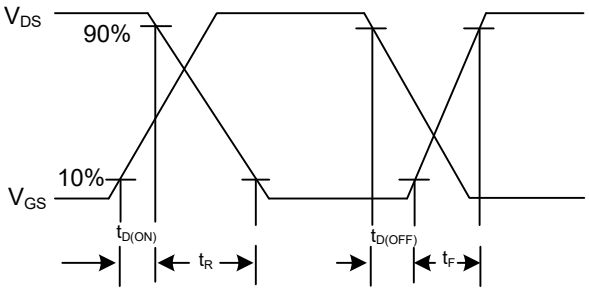


Peak Diode Recovery dv/dt Waveforms

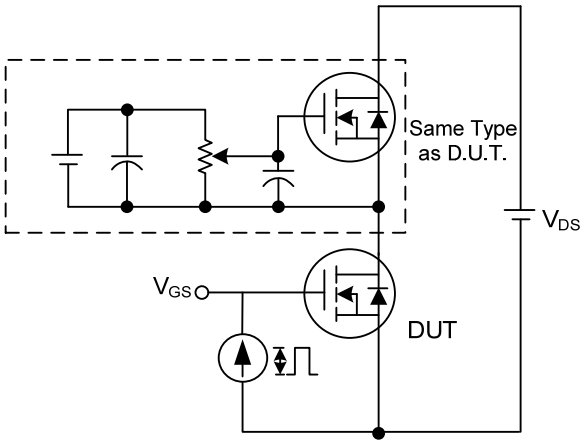
■ TEST CIRCUITS AND WAVEFORMS (Cont.)



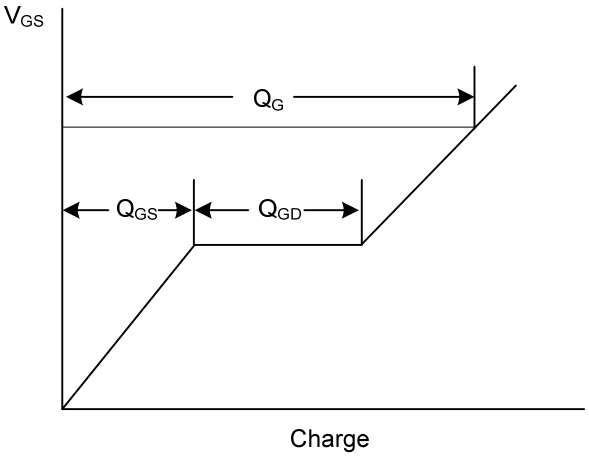
Switching Test Circuit



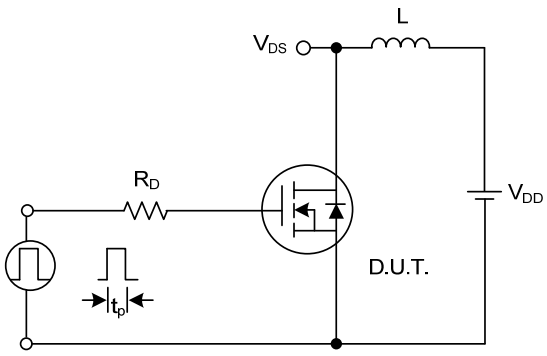
Switching Waveforms



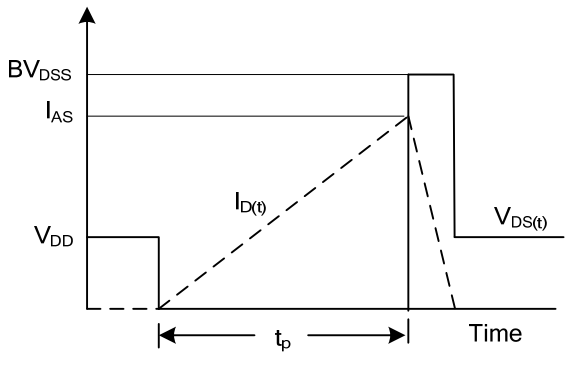
Gate Charge Test Circuit



Gate Charge Waveform



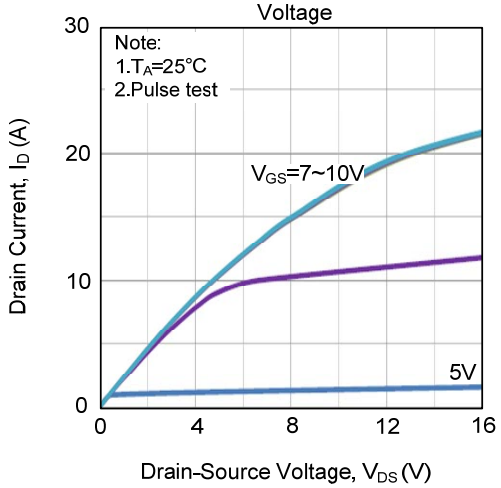
Unclamped Inductive Switching Test Circuit



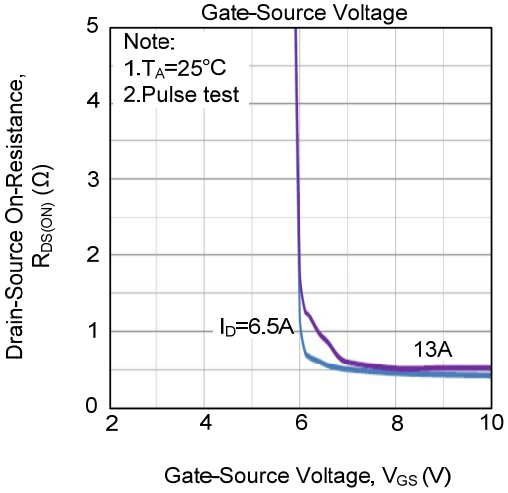
Unclamped Inductive Switching Waveforms

■ TYPICAL CHARACTERISTICS

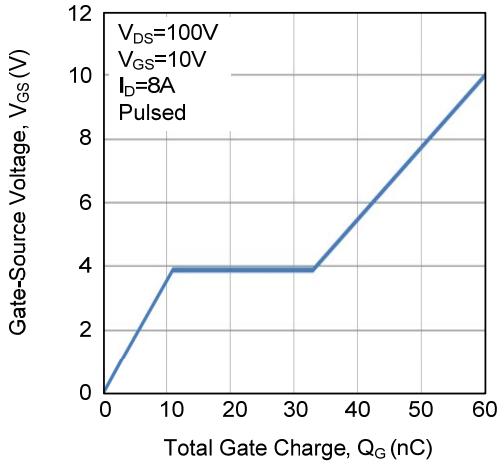
Drain Current vs. Drain-Source Voltage



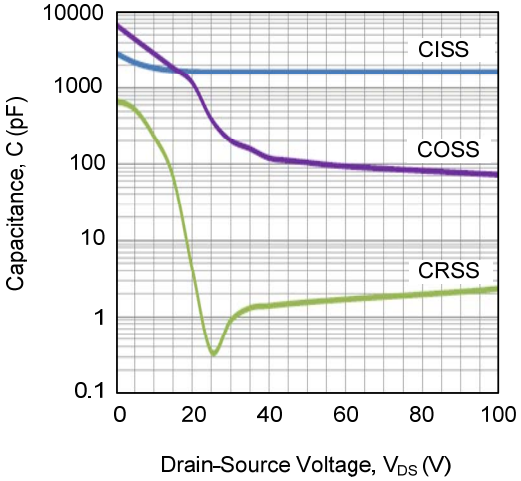
Drain-Source On-Resistance vs. Gate-Source Voltage



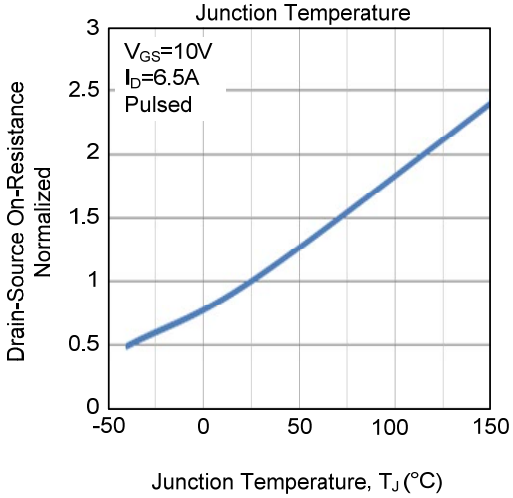
Gate Charge Characteristics



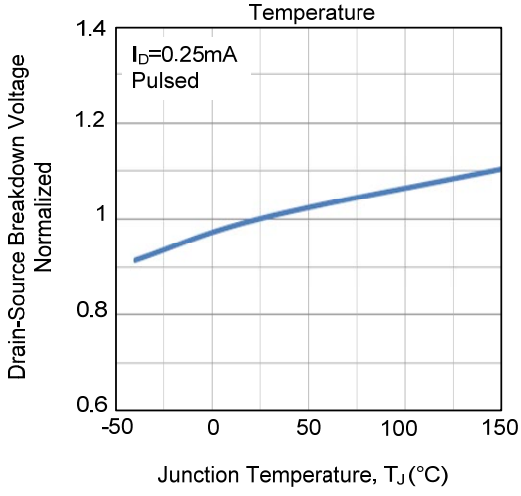
Capacitance Characteristics



Drain-Source On-Resistance vs. Junction Temperature

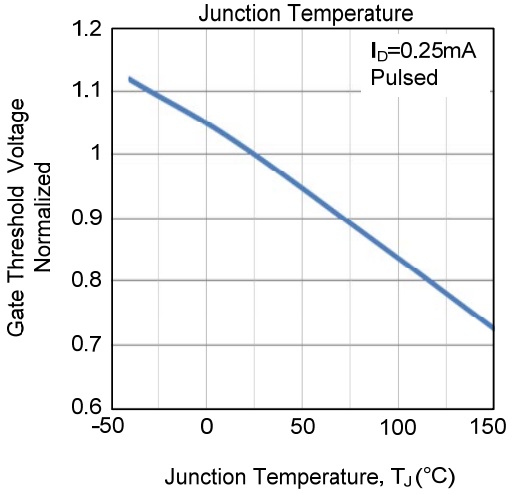


Breakdown Voltage vs. Junction Temperature

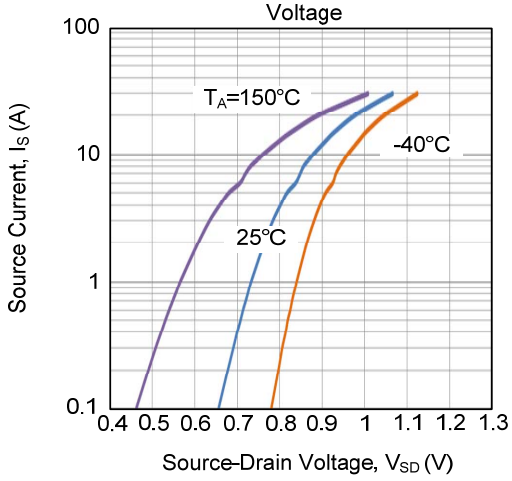


■ TYPICAL CHARACTERISTICS (Cont.)

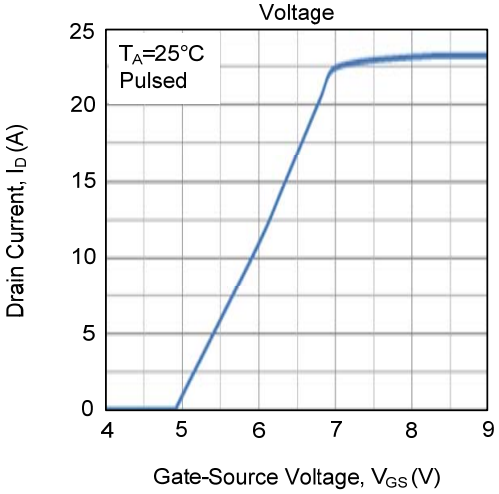
Gate Threshold Voltage vs. Junction Temperature



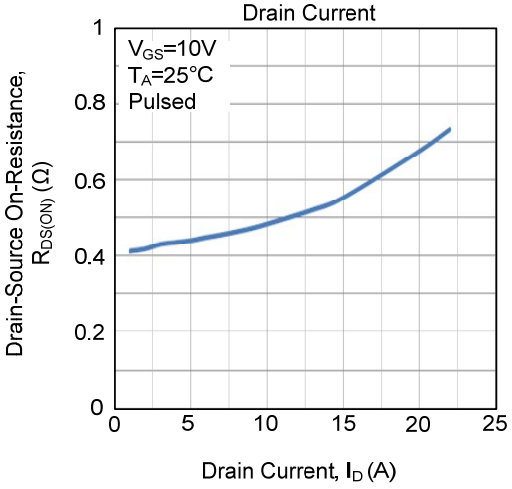
Source Current vs. Source-Drain Voltage



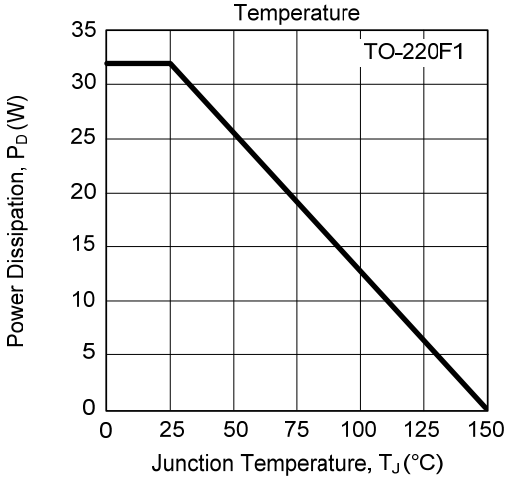
Drain Current vs. Gate-Source Voltage



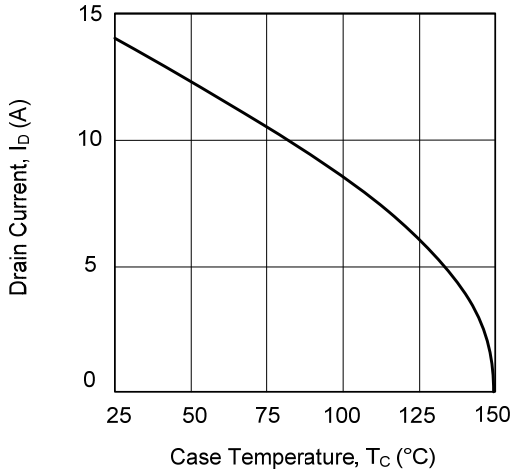
Drain-Source On-Resistance vs. Drain Current



Power Dissipation vs. Junction Temperature



Drain Current vs. Case Temperature



■ TYPICAL CHARACTERISTICS (Cont.)